

AUSSTELLERFORUM

Exhibitor's Forum

Dienstag · Tuesday, 11.3.2025

Zeit · Time Halle 2 · Hall 2, Stand 2-635

Session 1A, Start-up & Industry (Christoph Rommel)

10:00 – 10:15	Day 1 Kick-Off Empowering start-ups and transforming the industry
10:15 – 10:30	Industry Business Pitch Neumonda, Peter Pöchmüller – A Corporate Venturing Success Story
10:30 – 11:00	Pitch Session 1 ailcoustics (DE), Adesio (FR), bee produced (AT), denpaflux (DE), Eccelerators (AT)
11:00 – 11:30	Keynote – Industry Avnet Silica, Thomas Foj – The Evolution of Semiconductor Industry – Trends, Insights and Developments
11:30 – 11:45	Start-up & Industry – Success story I Würth Eisos & Start-up Hydrop System, Marion Wagner, Katrin Kreidel
11:45 – 12:15	Industry – Expert open Bosch, Johannes Grabowski - how to win large corporates as customers
12:15 – 12:45	Start-up & Industry – Success Story II Infineon + start-up, Lamin Ben-Hamdane
12:45 – 13:00	Start-up Innovation I Sykno, Benedict Scheiner
13:00 – 14:00	Mittagspause – Lunch break

Session 1B, Start-up & Industry (Christoph Rommel)

14:00 – 14:15	Day 1 afternoon Kick-Off Innovation through cooperation
14:15 – 14:30	Industry – Expert Three Success Stories of Partnering with Start-ups, open Bosch, Johannes Grabowski
14:30 – 15:00	Pitch Session 2 embeff (DE), Awentia (IT), es:saar (DE), Imavix (CZ), thistle (US)
15:00 – 15:30	Industry Expert Infineon Co-Innovation Program, Lamin Ben-Hamdane
15:30 – 15:45	Colaborate to innovate with Fraunhofer Fraunhofer Venture & Bavarian Chip-Design-Center, Florian Ascherl & Dr. Thorsten Edelhäuser
15:45 – 16:15	Pitch Session 3 Advanced Algorithms 4 Radar (SP), Inqode Solutions (DE), Metacomputing (CH), Tenxer Labs, Andalogic (TR)
16:30 – 17:30	embedded award NürnbergMesse, PirateX



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**17:30 –
18:00** **Networking**

Side Event – Start-up Demo Night

(BayStartUp, Z-Bau, Frankenstraße 200, 90461 Nürnberg)

Zeit · Time Halle 3 · Hall 3, Stand 3-611

10:00 – 10:30	Simplifying IoT Security: Understanding SESIP and the role of the Certification Body Lex Schoonen, Brightsight, 4-545
10:30 – 11:00	Advanced Storage for Industry Transformation Dr. Gibson Chen, Apacer, 1-310
11:00 – 11:30	Using Trace for Debugging and Runtime Analysis of Embedded Software with UDE® Jens Braune, PLS Programmierbare Logik & Systeme, 4-310
11:30 – 12:00	System Design and Use Cases of AI-Driven DSP Technologies in Modern Automotive Applications Casey Ng, Amit Kumar, Cadence, 4-219
12:00 – 12:30	A FOSS and CRA compliance policy: Exploiting the overlap Caren Kresse, OSADL, 4-168
12:30 – 13:30	Mittagspause – Lunch break
13:30 – 14:00	Making Every Microjoule Count for Edge AI Carlos Morales, AMBIQ MICRO, 4-581
14:00 – 14:30	Empower AI Applications with MediaTek Genio New Generation Tim Chick, MediaTek, 3-539
14:30 – 15:00	Building Secure Connected Products: Navigating the EU's Cyber Resilience Act with AAEON & Exein.io Daniele Cleri, AAEON, 1-306
15:00 – 15:30	Democratizing Centimeter-Level GNSS Precision for All Applications Mårten Ström, u-blox, 3-319
15:30 – 16:00	Product Innovation through Industrial UX - Modern Software Technologies for Human-Technology Interaction Justina Krawczyk, Rainer Dorau, Cloudflight Germany, 4-450
16:00 – 16:30	Join Forces for Next Intelligence Tim Park, DEEPX, 2-651
16:30 – 17:00	Efficient connectivity and security management for Industrial IoT Cyril PROYE, THALES, 3-630

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10:00 – 10:30	Control of application software-free peripherals and ECUs using 10BASE-T1S Jon Harper, On Semiconductor, 4A-260
10:30 – 11:00	How Context-Aware Computing Will Change The User Experience Vikram Gupta, Synaptics, 4A-259
11:00 – 11:30	New flexible SoC meets multiple smart metering and IoT wireless standards Philippe SIMONNET, STMicroelectronics, 4A-148
11:30 – 12:00	Wearables: The power of sensors in sports and healthcare Lisa TROLLO, STMicroelectronics, 4A-148
12:00 – 12:30	Scaling Performance and Reducing Latency in Edge Data Centers with PICMG® COM-HPC® Technologies Jess Isquith, Matthew Burns, PICMG, Samtec, 4A-324
12:30 – 13:30	Mittagspause – Lunch break
13:30 – 14:00	Evolution of Industrial Ethernet Topologies Volker Goller, ANALOG DEVICES, 4A-360
14:00 – 14:30	Diagnose your device without compromising security Jocelyn RICARD, STMicroelectronics, 4A-148
14:30 – 15:00	How to protect microcontroller secure boot with simple and robust isolation mechanism Frantz LEFRERE, STMicroelectronics, 4A-148
15:00 – 15:30	Benefits of RISC-V for future mobility and how Infineon commits to the market Thomas Schneid, Infineon, 4A-138
15:30 – 16:00	Storage architectures in automotive high-performance compute systems Steffen Buch, Micron, 3A-117
16:00 – 16:30	The power of graphical processing units into MCU-based systems Nicolas SANTINI, STMicroelectronics, 4A-148

Zeit · Time Halle 5 · Hall 5, Stand 5-210

10:00 – 10:30	Attackers Always Strike Back: Securing your Linux- and AI-Based Embedded Devices under Cyber Resilience Act Giorgiomaria Cicero, accelerat, 4-625
10:30 – 11:00	How to Build Reliability into Software-Defined “Stuff” Chuck Brokish, Greenhills, 4-325
11:00 – 11:30	Harnessing the power of GenAI in Automotive Sujeet Sreenivasan, Ignitarium, 5-156
11:30 – 12:30	Expert Panel: Are SoC Vendors Providing the Right Tools for Edge AI Developers? Manvinder Singh, Vice President Product Management, Qualcomm Zach Shelby, Chief Executive Officer (CEO), Edge Impulse Nicolas Gaude, AI Solutions Product Marketing Manager, STMicroelectronics Ali Osman Ors, Global Director AI Strategy and Technologies, NXP Host: George Grey, Foundries.io lead at Qualcomm

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12:30 – 13:30	Mittagspause – Lunch break
13:30 – 14:00	Transforming IoT with On-Device AI: Real-World Applications and Developer Success Stories Kedar Gharat, Qualcomm, 5-161
14:00 – 14:30	Technologies for Building and Deploying Secure Edge AI Workloads Tim Menesveta, ARM, 4-504
14:30 – 15:00	The Big Unveiling: AI for Embedded Power Circuit Generation Tomide Adesanmi, Circuit Mind, 4-215
15:00 – 15:30	Driving Success with DevSecOps and Platform Engineering: Unlocking Scalable Innovation Avijit Sinha, Jiani Zhang, Wind River, 5-253
15:30 – 16:00	Enhancing Wi-Fi networking support in Zephyr RTOS Yannis Glaropoulos, Nordic Semiconductor, 4A-310
16:00 – 16:30	Accelerating Automotive Development (showing virtual platforms including all abstraction layers up to application) Bernhard Rill, ARM, 4-504
16:30 – 17:00	Lisa Service: Smart optimization of Battery Lifetimes Isabelle Sourmey, SAFT, 5-122
17:00 – 17:30	Optimizations of AI Inference: The Role of ML Compiler and Hardware Innovations Milan Stankić, HTEC, 5-145

Mittwoch · Wednesday, 11.3.2025

Zeit · Time Halle 2 · Hall 2, Stand 2-635

Session 2A, Start-up & Investment (Carsten Rudolph)

10:00 – 10:15	Day 2 Kick-Off Financing start-ups and driving growth
10:15 – 10:45	Keynote – Investor Gitte Bedford, Bosch CVC – What investors are looking for
10:45 – 11:30	Pitch Competition Start-ups: filancore (DE), InCore Semiconductors (IN), Minerva Systems (IT), nextwave (KR), Periphery (GB), sandgrain (NL) Jury: Gitte Bedford – Bosch CVC, Markus Kückelhaus – HTGF, Carsten Rudolph – BayStartUp, Markus Matusek – Bayern Kapital
11:30 – 11:45	Industry Business Pitch Altium, Markus Bochynek
11:45 – 12:00	Pitch competition – winner announcement
12:00 – 12:30	Investor – Expert HTGF, Markus Kückelhaus – start-up seed investment
12:30 – 12:45	From Start-up to Corporate Renesas, Mark Dickson – how to make your start-up ready for strategic investors

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Zeit · Time Halle 2 · Hall 2, Stand 2-635

12:45 – 13:00 **Start-up Invest**
Sleeve, Mathias Ptacek – how to find an investor in a challenging industry

13:00 – 14:00 **Mittagspause – Lunch break**

Session 2B, Start-up Innovation (Christoph Rommel)

14:00 – 14:15 **Day 2 afternoon Kick-Off**
International start-up programs + Linda Steger (D2XCEL)

14:15 – 14:30 **Industry Business Pitch**
Avnet Silica, Mike Hartmann

14:30 – 15:00 **Pitch Session 4**
Efficientware (DE), 4TLAS (USA), five-d.ai (DE), SKANJAN SL (SP), Synthara (CH)

15:00 – 15:15 **Start-up Innovation II**
Minerva Systems SRL, Marco Solieri (CEO)

15:00 – 15:15 **Start-up Innovation III**
PCB Arts, Saber Kaygusuz

15:45 – 16:15 **Pitch Session 5**
embeff (DE), Awentia (IT), es:saar (DE), Imavix (CZ), thistle (US)

16:15 – 17:00 **Avnet Silica – Renesas Challenge 2025 – Award Ceremony**
Avnet Silica, Renesas, Altium, BayStartUp

17:00 – 17:30 **D2XCEL, – Start-up Pitches**
Clic recycle, STOFF2, HalioGen Power, Takeve, OBORTECH, MOBIQU, Develop, minimum energy, Firemesh, Naco Technologies, Spark e-Fuels, Gelectric

17:30 – 18:00 **Networking**

D2XCEL get together, NürnbergMesse, Start-up Area

Zeit · Time Halle 3 · Hall 3, Stand 3-611

9:00 – 9:30 **Rapid innovation: on-demand R&D teams for UWB, BLE, and emerging technologies**
Tymoteusz Polanski, Comarch, 5-321

9:30 – 10:00 **Finding Balance Between Cybersecurity Requirements and Market Needs when Adapting EU CRA and IEC 62443 for Industrial Devices**
Terry London, Proekspert, 4-380

10:00 – 10:30 **Automotive Cybersecurity with AURIX™**
Peter Pessl, Infineon, 4A-138

10:30 – 11:00 **FP 0,8 – Two and a half footprints in one mating face**
Thomas Schulze, PHOENIX CONTACT, 1-434

11:00 – 11:30 **The Current State of Automotive Software Development**
Jill Britton, Steve Howard, Perforce Software, 4-510

11:30 – 12:00 **Revolutionizing SoC Design: The Shift to Chiplet-Based Architectures**
Moshiko Emmer, Cadence, 4-219

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Zeit · Time Halle 3 · Hall 3, Stand 3-611

12:00 – 12:30	Winbond Customized Memory for Your Smart Life Sha-Ha Park, Winbond, 4A-635
12:30 – 13:30	Mittagspause – Lunch break
13:30 – 14:00	Scaling Interoperability Testing with ONELab – Conquering the Challenges of Arm SystemReady Certification Bill Fletcher, Linaro, 4-501
14:00 – 14:30	Rust for Embedded High-Integrity Systems Jose Ruiz, AdaCore, 4-148
14:30 – 15:00	Altium, 4-305
15:00 – 15:30	AI-Automated Fuzzing: How to Autonomously Detect Bugs in Embedded Software Dr. Khaled Yakdan, Code Intelligent, 5-378
15:30 – 16:00	NVIDIA Isaac ROS Ready: Accelerating AI-Enabled Robotics with Connect Tech Doruk Sönmez, Connect Tech, 3-260
16:00 – 16:30	Cybersecurity: regulations, standards, and solutions for embedded devices Manuel Crotti, Melchioni, 3-439

Zeit · Time Halle 3A · Hall 3A, Stand 3A-631

9:30 – 10:00	Channel Sounding - the Bluetooth LE feature for accurate and secure distance measuring Paweł Kanafek, Nordic Semiconductor, 4A-310
10:00 – 10:30	AI-Defined Vehicles are coming: automotive computing trends unleashing innovation Guil Marshall, ARM, 4-504
10:30 – 11:00	Dream big with tiny microcontrollers: the STM32N6 revolution in edge AI Edwin HILKENS, STMicroelectronics, 4A-148
11:00 – 11:30	Enabling next-gen embedded vision systems with MIPI I3C Marie-Charlotte LECLERC, STMicroelectronics, 4A-148
11:30 – 12:00	Expectations and Initiatives for Automotive Chiplets Stewart Bell, Socionext, 4A-628
12:00 – 12:30	Services und Individualisierung für Elektronikgehäuse Patrick Hartmann, PHOENIX CONTACT, 1-434
12:30 – 13:30	Mittagspause – Lunch break
13:30 – 14:00	The new nRF54L Series - longer battery lifetime of Bluetooth LE devices Sam Presley, Nordic Semiconductor, 4A-310
14:00 – 14:30	EU Cyber Resilience Act: Helping designers become fully compliant Laurent SUSTEK, STMicroelectronics, 4A-148

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14:30 – 15:00	Real world post-quantum cryptography for embedded systems Jacques FOURNIER, STMicroelectronics, 4A-148
15:00 – 15:30	Die Welt von Morgen: Zwischen selbstfahrenden Autos, Service-Robotik und persönlichen KI-Assistenten Prof. Dominik B.O. Bösl, Farnell, 3A-528
15:30 – 16:00	Single Pair Ethernet - available PHYs and Switches for the existing and upcoming standards Karl Lehnhoff, EBV Elektronik, 3A-125
16:00 – 16:30	How to manage your device's digital identity with a trusted and secure approach Benjamin BARATTE, STMicroelectronics, 4A-148
16:30 – 17:00	Sustainable, flexible semiconductor technology for embedded systems Drew Reidy, Pragmatic Semiconductor, 5-312

Zeit · Time Halle 5 · Hall 5, Stand 5-210

9:00 – 9:30	Unlock the Potential of Cloud Manufacturing for Your Brownfield Plant Fabio Oettl, Abhijith Raghavendra, Naveen Suryakumar, SUSE, 5-342
9:30 – 10:00	Transforming the Future with Real-Time Edge AI Avijit Sinha, Michael Maxey, Wind River, 5-253
10:00 – 10:30	Agile Transformation in Mechanical Engineering Matthias Müller, Oliver Krakow, Cloudflight Germany, 4-450
10:30 – 11:00	Modern Methods & Tools to Become a Development & Debugging Hero Chuck Brokish, Greenhills, 4-325
11:00 – 11:30	Tools for development-related precompliance troubleshooting Konstantin Uhle-Wettler, Langer EMV-Technik, 5-270
11:30 – 12:30	Expert Panel: Implementing the Cyber Resilience Act (CRA) Dr. Julien Bernet, Head of Security, Witekio Mark Hermeling, VP of Global Solutions Engineering, CodeSecure Caren Kresse, Member of the Board of Directors, OSADL Host: Prof. Dirk Pesch, ewC Steering Committee, University College Cork
12:30 – 13:30	Mittagspause – Lunch break
13:30 – 14:00	High-Performance, Small Form Factor Open Standard SoMs Matthew Burns, Samtec, 4A-324
14:00 – 14:30	Making the Software Defined Vehicle real Robert Day, ARM, 4-504
14:30 – 15:00	Emerging Applications with New GigaDevice's Flash Memory Products Conrado Canio, GigaDevice Semiconductor, 5-129
15:00 – 15:30	In-field provisioning and life cycle management for microcontrollers in the era of CRA Gordon Fairley, Kudelski IoT, Ren Sun, GigaDevice Semiconductor, 5-129
15:30 – 16:00	AURIX(TM) TC4x: Leading the Way in Safe, Secured and Smart Mobility Karel Heurtefeux, Infineon, 4A-138

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16:00 – 16:30	Building the Software Stack for Edge AI Christophe Fava-Rivi, ARM, 4-504
16:30 – 17:00	Addressing Security Challenges with Open Architecture Security Elements Jan Pleskac, TROPIC SQUARE, 5-373

Donnerstag · Thursday, 13.3.2025

Zeit · Time Halle 2 · Hall 2, Stand 2-635

Session 3, Start-up Excellence (Christoph Rommel)

10:00 – 10:15	Day 3 Kick-Off Start-ups in Focus: Innovation, Passion, Impact
10:15 – 10:30	Industry Business Pitch Renesas, Andreas Bier, Vinod Dosapa – Innovate with Renesas: Advanced Microcontroller Solutions for Start-ups
10:30 – 11:00	Pitch Session 6 HS Devices (RS), Periphery (UK), nextwave (KR), filancore (DE), tekhne (SP)
11:00 – 11:30	Industry Business Pitch NXP, Georg Olma - Brighter Trends – Start-ups x NXP
11:30 – 12:00	Pitch Session 7 SandGrain (NL), inCore Semiconductors (IN), Wirenboard (AM), baya systems (US), Mantispectra (NL)
12:00 – 12:15	Start-up Innovation IIII Perovskia Solar
12:15 – 12:30	NürnbergMesse Welcome address
12:30 – 13:00	Opening message Secretary of State Gotthardt
13:00 – 14:00	women4ew NürnbergMesse
	Secretary of state guided tour in start-up City
14:00 – 15:00	women4ew Get-together in start-up City
	Day 3 afternoon Kick-Off
	Start-up Pitch Session 7 ai coustics (DE), Adesio (FR), bee produced (AT), denpaflux (DE), Eccelerators (AT), oX2A (CZ), Silicon Signals (IN)
15:00 – 15:30	student rallye – winner announcement NürnbergMesse, PirateX
15:30 – 18:00	Networking

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Zeit · Time Halle 3 · Hall 3, Stand 3-611

10:00 – 10:30	Getting Up to Speed with RTOS-based Firmware Development Ali Anjaani, Nordic Semiconductor, 4A-310
10:30 – 11:00	Production of PCB prototypes: Etching, milling, laser processing Jan-Hendrik Guttman, LPKF Laser & Electronics SE, 2-100
11:00 – 11:30	Avoiding Patent Conflicts in Device Software Development Andy Walter, Cloudflight Germany, 4-450
11:30 – 12:00	From RTOS to Linux: Navigating OS Options for the Intelligent Edge Michel Chabroux, Wind River, 5-253

Zeit · Time Halle 3A · Hall 3A, Stand 3A-631

10:00 – 10:30	Sensors: Easily bring intelligence to the edge Lisa TROLLO, STMicroelectronics, 4A-148
10:30 – 11:00	LPWAN: which technology best fits IIoT use cases? Filippo COLAIANNI, STMicroelectronics, 4A-148
11:00 – 11:30	Decision Making at the Edge with AI-Driven Sensors Tom Sharkey, ANALOG DEVICES, 4A-360
11:30 – 12:00	How to Balance System Energy Efficiency, Carbon Reduction, and Stability with Winbond's new WQFN12 William Chen, Winbond, 4A-635
12:00 – 12:30	Releasing the AI bottleneck with the right memory Wil Florentino, Micron, 3A-117

Zeit · Time Halle 5 · Hall 5, Stand 5-210

10:00 – 10:30	Easy-to-use microcontroller configuration and evaluation with AURIX (TM) Configuration Studio Stefan Kluwe, Infineon, 4A-138
10:30 – 11:00	Enabling the Next Generation of Optical Connectivity in Embedded Applications Matthew Burns, Samtec, 4A-324
11:30 – 12:30	Expert Panel: Enabling the Next Generation of Optical Connectivity in Embedded Applications Dr. Jean Caron, Vice President Sales & Support EMEA, euresys (a TKH Vision brand) Yash Kharia, Director Product Management, Industrial Embedded IoT Business, Qualcomm Dr. Martin Klenke, Director Business Development, Teledyne Imaging Jan-Erik Schmitt, Vice President, Vision Components Jan-Friso Blaqui�re, Vice President Sales, Hailo Host: David L�h, Editor-in-Chief, inspect, Wiley-VCH

Alle Angaben ohne Gew hr.  nderungen vorbehalten. *No responsibility accepted for errors. Subject to change.* Stand/Date: 24.1.2025

Das gesamte Programm des Ausstellerforums und der Expert Panels finden Sie auch unter www.embedded-world.de/programm und auf Informations-Stelen vor Ort.

Please visit www.embedded-world.de/programme as well as at the on-site information pillars to find the programme of the Exhibitor's Forum as well as of the Expert Panels.